

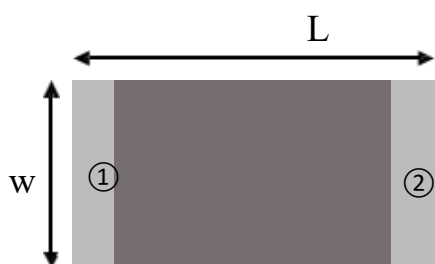
Features

- 1.Surface Mounted Devices with a small dimension of 1.6 x 0.8 x 0.8 mm meet futureminiaturization trend.
- 2,Embedded and LTCC(low temperature co-fired ceramic) technology is able to integrate with system design as well as beatifying the housing of final product.
3. High stability and low tolerance.

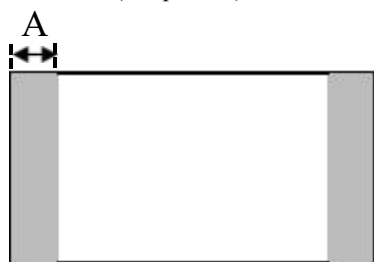
Applications

1. Bluetooth
2. Wireless LAN
3. ISMband 2.4GHz wireless applications

Dimensions (Unit: mm)



(Top View)



(Bottom View)

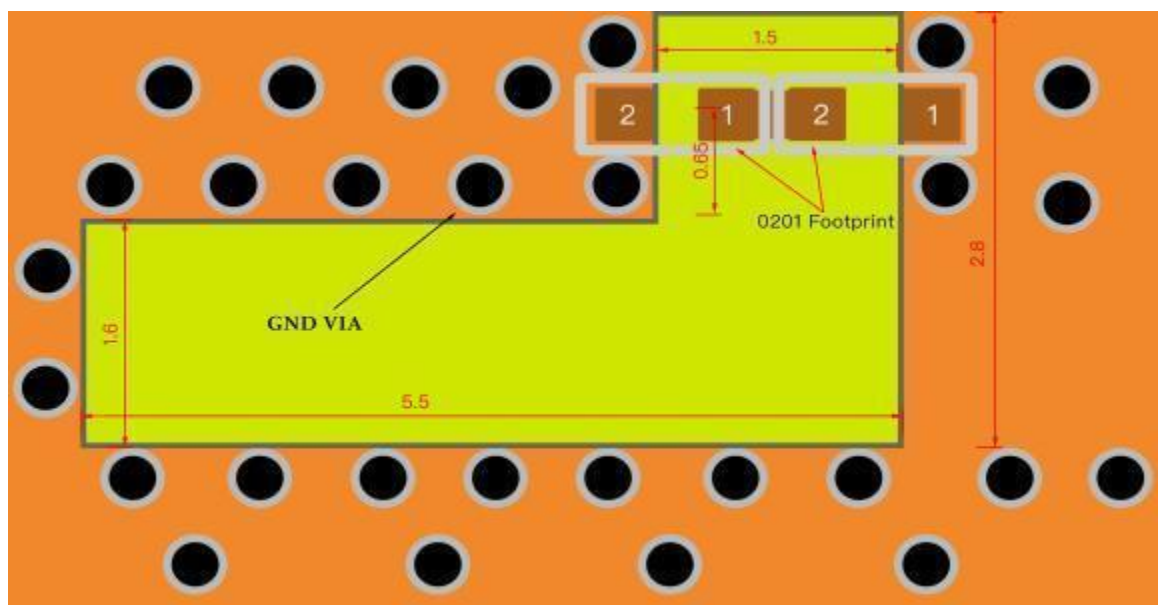
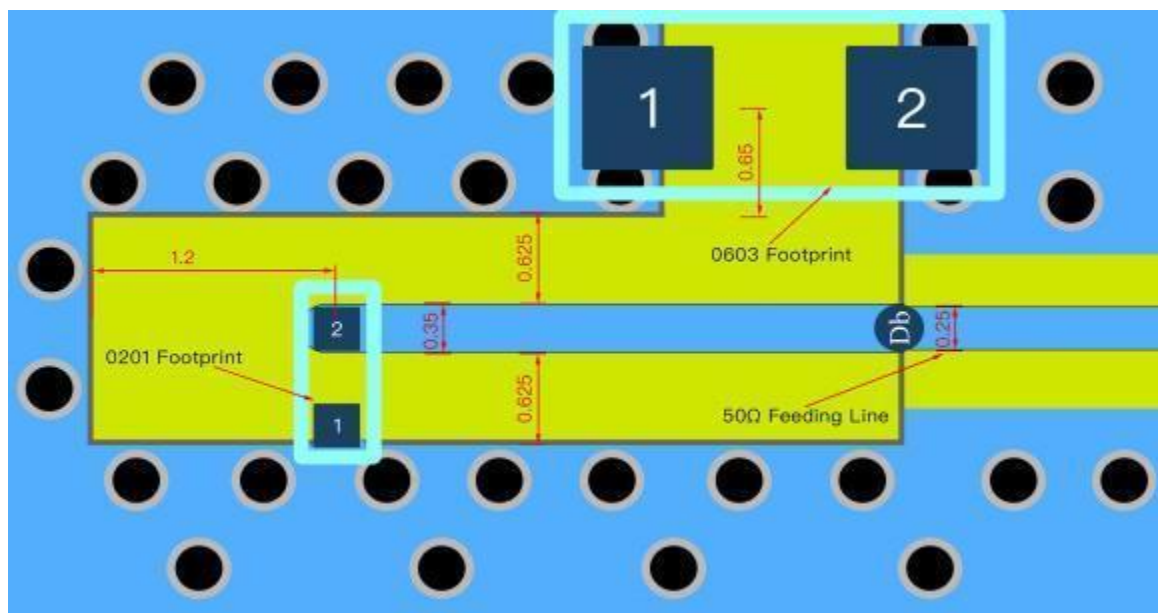
Number	Terminal Name
①	INPUT
②	NC



(Side View)

Symbols	L	W	T	A
Dimensions	1.60±0.20	0.80±0.20	0.80±0.20	0.30±0.10

Evaluation Board and Matching Circuits



P/N:HYX160808D09

S11-Parameter



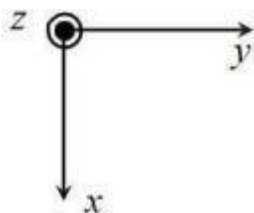
Frequency(MHz)	2400	2450	2480	2500
VSWR	1.56	1.16	1.48	1.79

Electrical Characteristics

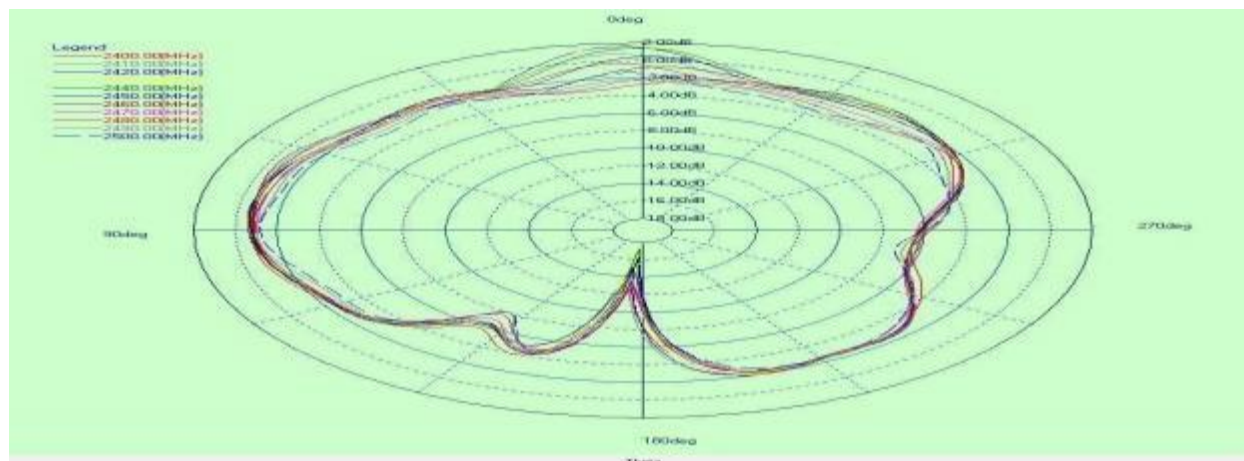
Item	Feature	Specification
1	Frequency	2400-2490MHz
2	Bandwidth	> 120MHz
3	Peak gain	2dBi
4	VSWR	<2
5	Polarization	Linear
6	Azimuth beamwidth	Omnidirectional
7	Impedance	50 Ω
NOTE: The specification is defined based on the test board dimension.		

Radiation Pattern

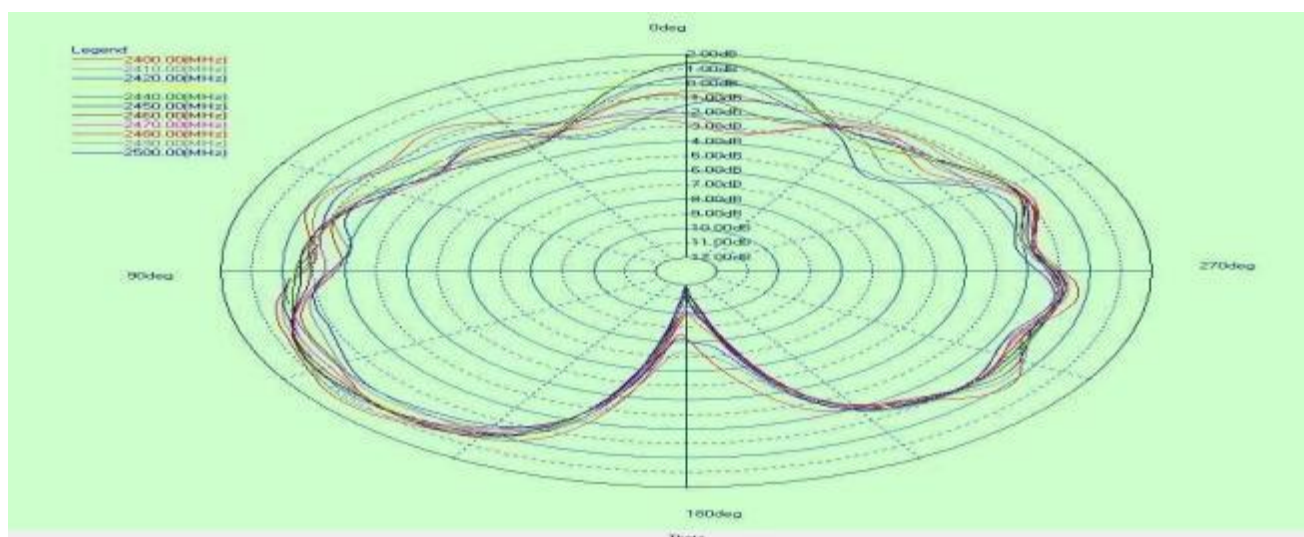
coordinates:



Y-Z Plane

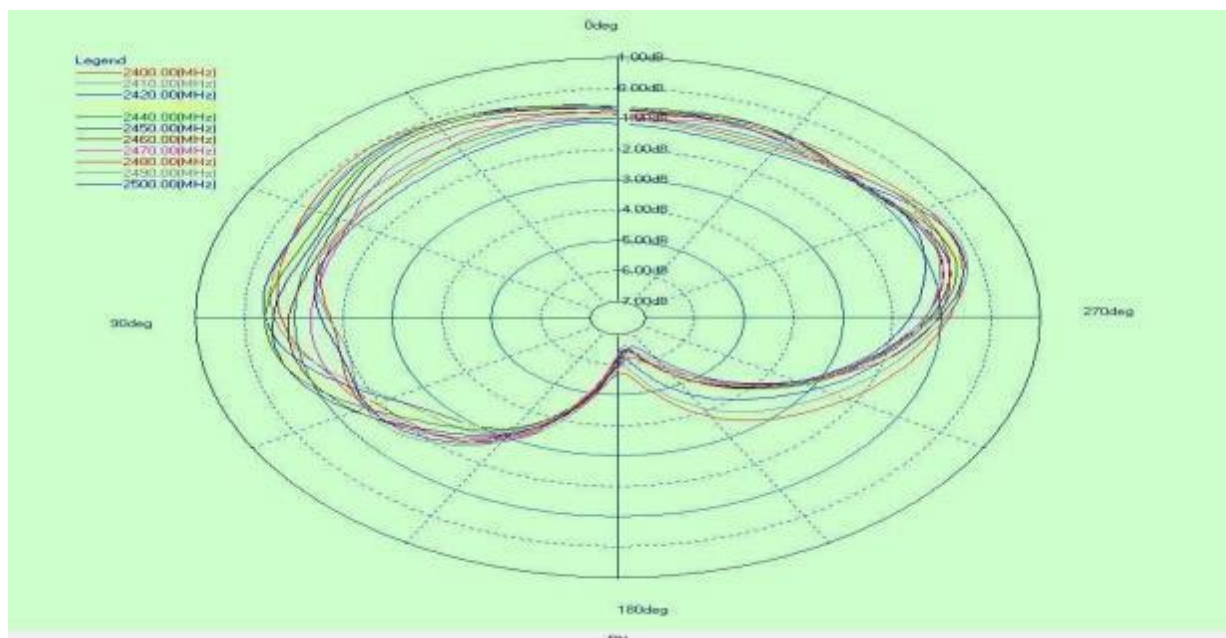


X-Z Plane



P/N:HYX160808D09

X-Y Plane



Frequency	2400MHZ	2450MHZ	2490MHZ
Avg. gain	1.30	0.93	0.45
Peak gain	2	1.89	1.96
Efficiency	57%	54%	53%

P/N:HYX160808D09

Dependability Test

	Test Temperature:	25℃±3℃
Operating Temperature	-25℃~+85℃	
Temperature	5~40℃	
Relative Humidity	20~70%	

Moisture Proof

Temperature: 40±2℃ Humidity: 90~95% RH

Duration: 500h

Recovery conditions: Room temperature Recovery Time: 24h (Class1) or 48h (Class2)

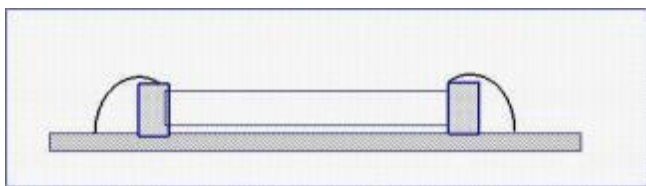
Solderability

At least 95% of the terminal electrode is covered by new solder. Preheating conditions: 80 to 120℃ ; 10~30s.

Solder Temperature: 235±5℃ Duration: 2±0.5s, Solder Temperature: 245±5℃ Duration: 2±0.5s

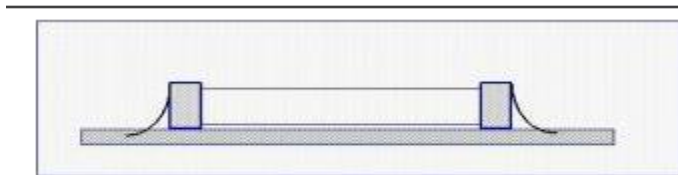
Optimum Solder Amount for Reflow Soldering

Too much solder



Cracks tend to occur due to large stress.

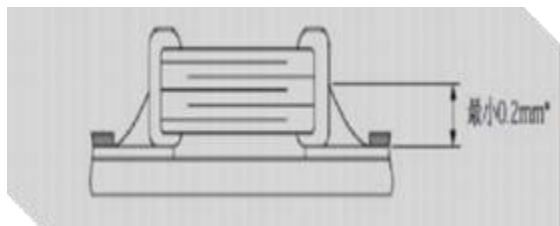
Not enough solder



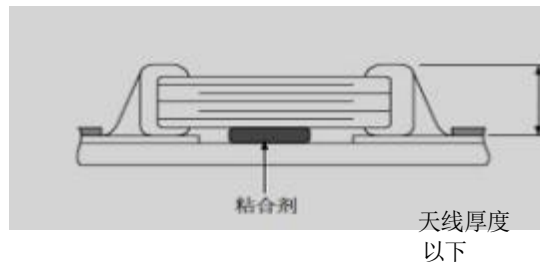
Weak holding force may cause bad connection between the capacitor and PCB.

Recommended Soldering amounts

The optimal solder fillet amounts for re-flow soldering



The optimal solder fillet amounts for wave soldering



P/N:HYX160808D09

Temperature Cycle Test

10±1S Applied Force: 5N Duration: 10±1S

Preheating conditions: up-category temperature, 1h

Recovery time: 24±1h

Initial Measurement

Cycling Times: 5 times, 1 cycle, 4 steps:

阶段	温度 (℃)	时间 (分钟)
第1步	下限温度 (MP03X76X75X06X25R-55 Y3V-25 Z5U-10)	30
第2步	常温 (+20)	2~3
第3步	上限温度 (MP03X76X75-125 Y3V-25U1X5R-85 J6S-105)	30
第4步	常温 (+20)	2~3

Resistanceto SolderingHeat

Preheating80 to 120℃; 10~30s.SolderTemperature:235±5℃ Duration:2±0.5s , SolderTemperature:245±5℃ Duration:2±0.5s, Preheating100to200℃;10±2min.

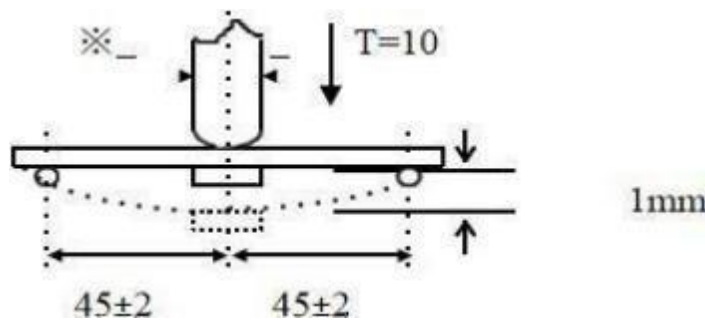
Solder Temperature: 265±5℃ Duration: 10±1s

Clean the capacitor with solvent and examine it with a 10X(min.) microscope.

Recovery Time: 24±2h

Recovery condition: Room temperature

Resistance to Flexure ofSubstrate

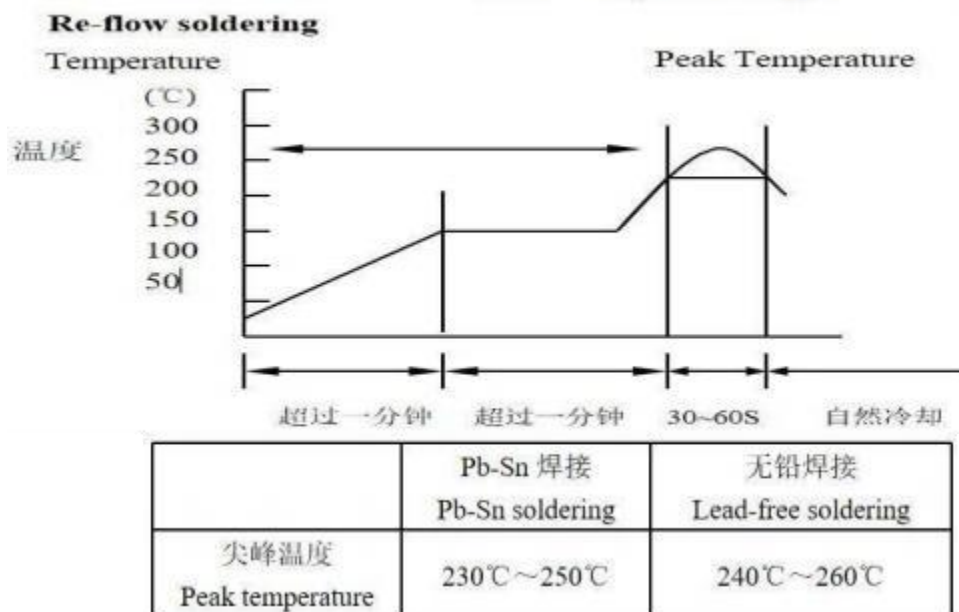


TestBoard: Al₂O₃ orPCB Warp: 1mm Speed: 0.5mm/sec.

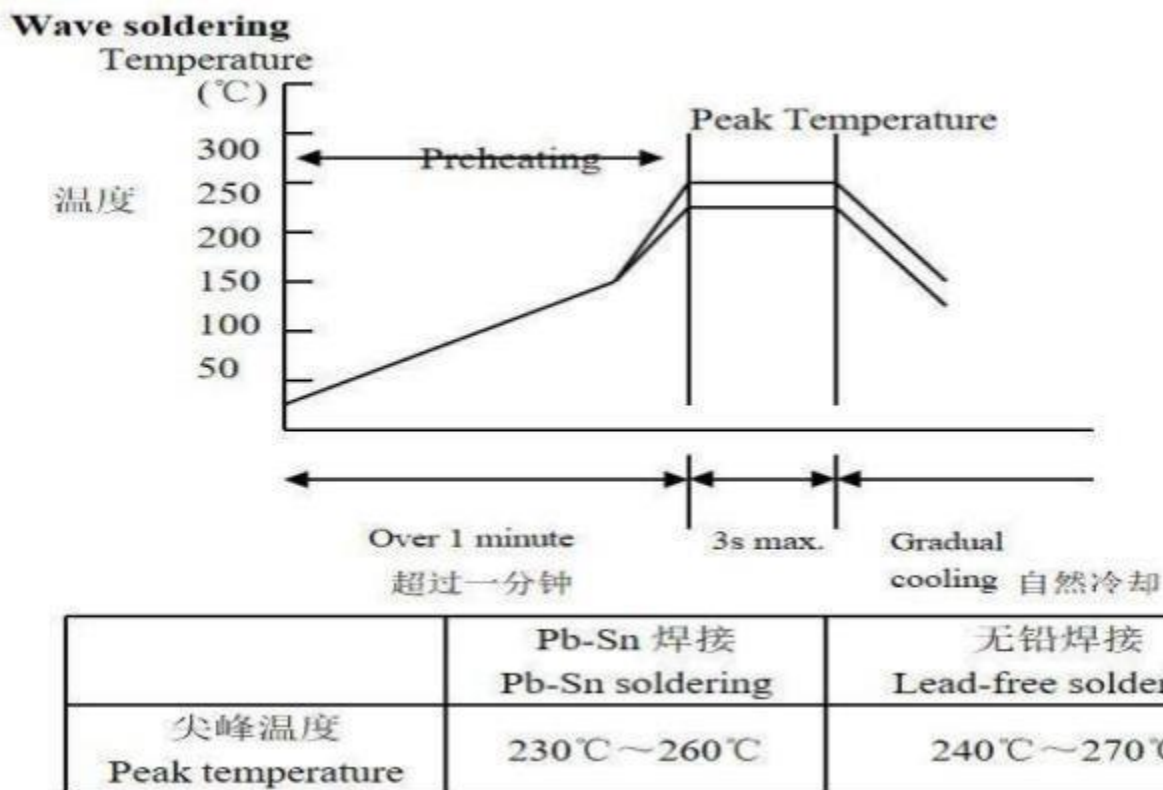
Unit: mm

The measurement should be made with the board in the bending position.

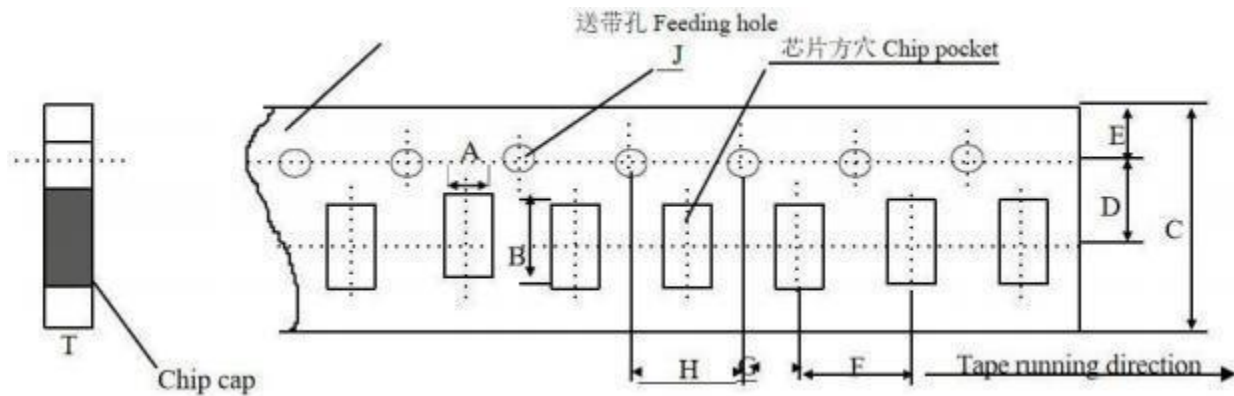
The temperature profile for soldering



While in preheating, please keep the temperature difference between soldering temperature and surface temperature of chips as: $T \leq 150^{\circ}\text{C}$.



Dimensions of paper taping for 0603 types



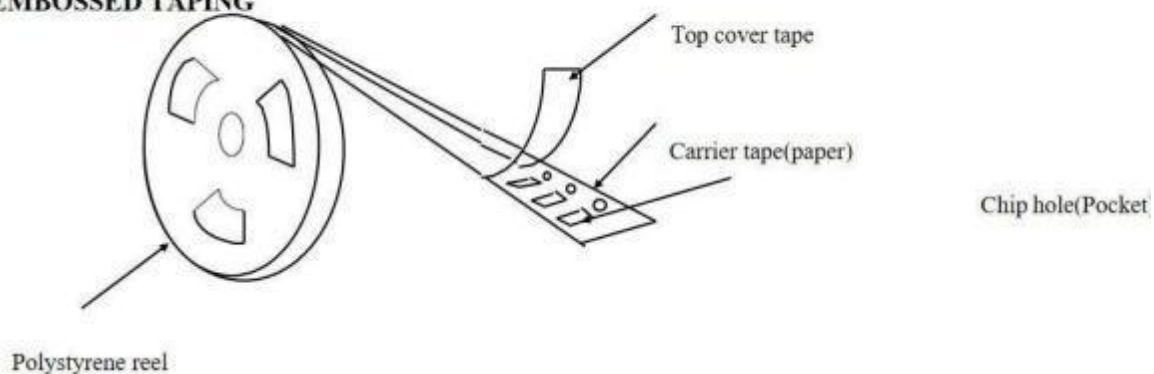
Unit: mm

代号 Code 纸带规格 papersize	A	B	C	D*	E	F	G*	H	J	T
0603	1.10 ±0.10	1.90 ±0.10	8.00 ±0.10	3.50 ±0.05	1.75 ±0.10	4.00 ±0.10	2.00 ±0.10	4.00 ±0.10	1.50 -0/+0.10	1.10 Max

Reel (4000 pcs/Reel)

Note: The place with * means where needs exactly dimensions.

EMBOSED TAPING



Storage Period

The guaranteed period for solderability is 6 months (Under deliver package condition). Temperature 5~40℃ /Relative Humidity 20~70%

the address: 1903-1905, Building 2, Jiufang Square, Tie Zai Road, Gongle Community, Xixiang Street, Bao'an District, Shenzhen TEL: 0755- 23591525, FAX: 0755-23591525